Materials Declaration

Package	PDIP
Body Size	300 mils
LeadCount	8
Option	Pb-free, Halide free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica	86	2.82 E-01	567886
Epoxy Resin	7.5	2.46 E-02	49525
Phenol Resin	4	1.31 E-02	26413
Epoxy Cresol Novolac	2	6.57 E-03	13207
Carbon Black	0.5	1.64 E-03	3302
Subtotal		3.28 E-01	660333

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.49 E-01	299925
Fe	2.35	3.60 E-03	7229
Zn	0.12	1.84 E-04	369
P	0.03	4.59 E-05	92
Subtotal		1.53 E-01	307615

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.55 E-03	3107

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.07 E-02	21585

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.60 E-04	523

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.50 E-03	5027

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	7.20 E-04	1448
Resin	15	1.35 E-04	271
Curing agent and hardener	5	4.50 E-05	90
Subtotal		9.00 E-04	1810

Package Totals

Weight (g)	PPM
4.97 E-01	1000000

N-01

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any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	PDIP
Body Size	300 mils
LeadCount	8
Option	with Pb, Halide-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica	86	2.82 E-01	567886
Epoxy Resin	7.5	2.46 E-02	49525
Phenol Resin	4	1.31 E-02	26413
Epoxy Cresol Novolac	2	6.57 E-03	13207
Carbon Black	0.5	1.64 E-03	3302
Subtotal		3.28 E-01	660333

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.49 E-01	299925
Fe	2.35	3.60 E-03	7229
Zn	0.12	1.84 E-04	369
P	0.03	4.59 E-05	92
Subtotal		1.53 E-01	307615

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.55 E-03	3107

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	9.12 E-03	18347
Pb	15	1.61 E-03	3238
Subtotal		1.07 E-02	21585

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.60 E-04	523

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.50 E-03	5027

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	7.20 E-04	1448
Resin	15	1.35 E-04	271
Curing agent and hardener	5	4.50 E-05	90
Subtotal		9.00 E-04	1810

Package Totals

Weight (g)	PPM
4.97 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

N-02

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ADI Proprietary

Materials Declaration

Package	PDIP
Body Size	300 mils
LeadCount	8
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	72	1.69 E-01	380178
Epoxy Cresol Novolac	16	3.76 E-02	84584
Phenol Novolac	8	1.88 E-02	42292
Sb2O3	2.2	5.17 E-03	11630
Brominated Resin	1.6	3.76 E-03	8458
Carbon Black	0.2	4.70 E-04	1057
Subtotal		2.35 E-01	528200

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.86 E-01	418421
Fe	2.35	4.48 E-03	10078
Zn	0.12	5.72 E-05	129
P	0.03	2.29 E-04	515
Subtotal		1.91 E-01	429143

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.67 E-04	1950

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	8.15 E-03	18334

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	9.83 E-05	221

Chip

	% of Chip	Weight (g)	PPM
Si	100	9.08 E-03	20426

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	6.14 E-04	1380
Resin	15	1.15 E-04	259
Curing agent and hardener	5	3.83 E-05	86
Subtotal		7.67 E-04	1725

Package Totals

Weight (g)	PPM
4.45 E-01	1000000

N-03

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ADI Proprietary

Materials Declaration

Package	PDIP
Body Size	300 mils
LeadCount	8
Option	with Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	72	1.69 E-01	380187
Epoxy Cresol Novolac	16	3.76 E-02	84586
Phenol Novolac	8	1.88 E-02	42293
Sb2O3	2.2	5.17 E-03	11631
Brominated Resin	1.6	3.76 E-03	8459
Carbon Black	0.2	4.70 E-04	1057
Subtotal		2.35 E-01	528212

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.86 E-01	418430
Fe	2.35	4.48 E-03	10078
Zn	0.12	5.72 E-05	129
P	0.03	2.29 E-04	515
Subtotal		1.91 E-01	429153

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.67 E-04	1950

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	6.92 E-03	15567
Pb	15	1.22 E-03	2745
Subtotal		8.14 E-03	18312

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	9.83 E-05	221

Chip

	% of Chip	Weight (g)	PPM
Si	100	9.08 E-03	20427

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	6.14 E-04	1380
Resin	15	1.15 E-04	259
Curing agent and hardener	5	3.83 E-05	86
Subtotal		7.67 E-04	1725

Package Totals

Weight (g)	PPM
4.45 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

N-04

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